

SN54HC623, SN74HC623 OCTAL BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

SCLS149C – DECEMBER 1982 – REVISED DECEMBER 2002

- Wide Operating Voltage Range of 2 V to 6 V
- High-Current 3-State Outputs Can Drive Up To 15 LSTTL Loads
- Low Power Consumption, 80- μ A Max I_{CC}
- Typical $t_{pd} = 8$ ns
- ± 6 -mA Output Drive at 5 V
- Low Input Current of 1 μ A Max
- Lock Bus-Latch Capability
- True Logic

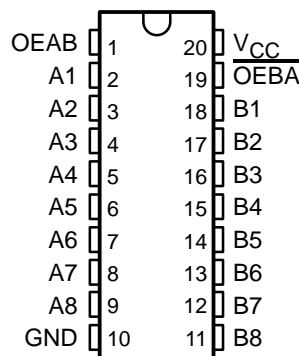
description/ordering information

These octal bus transceivers are designed for asynchronous two-way communication between data buses. The control-function implementation allows for maximum flexibility in timing.

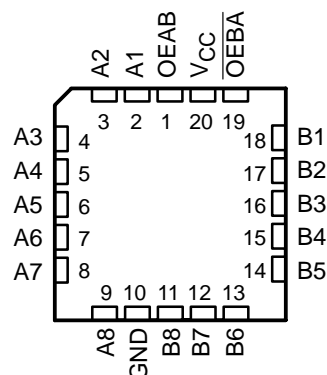
The 'HC623 devices allow data transmission from the A bus to the B bus or from the B bus to the A bus, depending upon the logic levels at the output-enable (OEAB and \overline{OEBA}) inputs.

OEAB and \overline{OEBA} disable the device so that the buses are effectively isolated. The dual-enable configuration gives the transceivers the capability to store data by simultaneously enabling OEAB and \overline{OEBA} . Each output reinforces its input in this transceiver configuration. When both OEAB and \overline{OEBA} are enabled and all other data sources to the two sets of bus lines are in the high-impedance state, both sets of bus lines (16 total) remain at their last states. The 8-bit codes appearing on the two sets of buses are identical.

SN54HC623 . . . J OR W PACKAGE
SN74HC623 . . . DW, N, OR NS PACKAGE
(TOP VIEW)



SN54HC623 . . . FK PACKAGE
(TOP VIEW)



ORDERING INFORMATION

TA	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	PDIP – N	Tube	SN74HC623N	SN74HC623N
	SOIC – DW	Tube	SN74HC623DW	HC623
		Tape and reel	SN74HC623DWR	
	SOP – NS	Tape and reel	SN74HC623NSR	HC623
-55°C to 125°C	CDIP – J	Tube	SNJ54HC623J	SNJ54HC623J
	CFP – W	Tube	SNJ54HC623W	SNJ54HC623W
	LCCC – FK	Tube	SNJ54HC623FK	SNJ54HC623FK

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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**TEXAS
INSTRUMENTS**

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INPUTS		OPERATION
OEBA	OEAB	
L	L	B data to A bus
H	H	A data to B bus
H	L	Isolation
L	H	B data to A bus, A data to B bus

The diagram illustrates the internal logic of the 74VHC04B, which consists of six inverters. The inputs and outputs are labeled as follows:

- OEBA** (Pin 19): Input to the first inverter.
- OEAB** (Pin 1): Input to the second inverter.
- A1** (Pin 2): Input to the third inverter.
- B1** (Pin 18): Output of the third inverter.

The internal structure shows the following connections:

- The output of the first inverter (OEBA) is connected to the input of the second inverter (OEAB).
- The output of the second inverter (OEAB) is connected to the input of the third inverter (A1).
- The output of the third inverter (A1) is connected to the input of the fourth inverter (B1).
- The output of the fourth inverter (B1) is connected to the input of the fifth inverter.
- The output of the fifth inverter is connected to the input of the sixth inverter.
- The output of the sixth inverter is connected to the input of the first inverter (OEBA).

The diagram also shows the internal logic gates (inverters) and the output signals (B1, B2, B3, B4, B5, B6) connected to the pins (18, 17, 16, 15, 14, 13).

Supply voltage range, V_{CC}	−0.5 V to 7 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) (see Note 1)	±20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) (see Note 1)	±20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	±35 mA
Continuous current through V_{CC} or GND	±70 mA
Package thermal impedance, θ_{JA} (see Note 2): DW package	58°C/W
N package	69°C/W
NS package	60°C/W
Storage temperature range, T_{stg}	−65°C to 150°C

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. The package thermal impedance is calculated in accordance with JEDEC 51-7.

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recommended operating conditions (see Note 3)

			SN54HC623			SN74HC623			UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	
V _{CC}	Supply voltage		2	5	6	2	5	6	V
V _{IH}	High-level input voltage	V _{CC} = 2 V	1.5			1.5			V
		V _{CC} = 4.5 V	3.15			3.15			
		V _{CC} = 6 V	4.2			4.2			
V _{IL}	Low-level input voltage	V _{CC} = 2 V	0.5			0.5			V
		V _{CC} = 4.5 V	1.35			1.35			
		V _{CC} = 6 V	1.8			1.8			
V _I	Input voltage		0	V _{CC}		0	V _{CC}		V
V _O	Output voltage		0	V _{CC}		0	V _{CC}		V
Δt/Δv	Input transition rise/fall time	V _{CC} = 2 V	1000			1000			ns
		V _{CC} = 4.5 V	500			500			
		V _{CC} = 6 V	400			400			
T _A	Operating free-air temperature		−55	125		−40	85		°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		V _{CC}	T _A = 25°C			SN54HC623		SN74HC623		UNIT
					MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V _{OH}		V _I = V _{IH} or V _{IL}	I _{OH} = –20 μ A	2 V	1.9	1.998		1.9		1.9		V
				4.5 V	4.4	4.499		4.4		4.4		
				6 V	5.9	5.999		5.9		5.9		
			I _{OH} = –6 mA	4.5 V	3.98	4.3		3.7		3.84		
			I _{OH} = –7.8 mA	6 V	5.48	5.8		5.2		5.34		
V _{OL}		V _I = V _{IH} or V _{IL}	I _{OL} = 20 μ A	2 V		0.002	0.1		0.1		0.1	V
				4.5 V		0.001	0.1		0.1		0.1	
				6 V		0.001	0.1		0.1		0.1	
			I _{OL} = 6 mA	4.5 V		0.17	0.26		0.4		0.33	
			I _{OL} = 7.8 mA	6 V		0.15	0.26		0.4		0.33	
I _I	OEAB or OEBA	V _I = V _{CC} or 0		6 V		±0.1	±100		±1000		±1000	nA
I _{OZ}	A or B	V _O = V _{CC} or 0		6 V		±0.01	±0.5		±10		±5	μ A
I _{CC}		V _I = V _{CC} or 0, I _O = 0		6 V			8		160		80	μ A
C _i	OEAB or OEBA			2 V to 6 V		3	10		10		10	pF

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SN54HC623, SN74HC623

OCTAL BUS TRANSCEIVERS

WITH 3-STATE OUTPUTS

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switching characteristics over recommended operating free-air temperature range, $C_L = 50$ pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC}	$T_A = 25^\circ\text{C}$			SN54HC623		SN74HC623		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{pd}	A or B	B or A	2 V		29	105		160		130	ns
			4.5 V		10	21		32		26	
			6 V		8	18		27		22	
t_{en}	\overline{OEBA}	A	2 V		112	210		315		265	ns
			4.5 V		27	42		63		53	
			6 V		20	36		54		45	
t_{dis}	\overline{OEBA}	A	2 V		40	150		225		190	ns
			4.5 V		18	30		45		38	
			6 V		16	26		38		32	
t_{en}	OEAB	B	2 V		112	210		315		265	ns
			4.5 V		27	42		63		53	
			6 V		20	36		54		45	
t_{dis}	OEAB	B	2 V		40	150		225		190	ns
			4.5 V		18	30		45		38	
			6 V		16	26		38		32	
t_t		A or B	2 V		20	60		90		75	ns
			4.5 V		8	12		18		15	
			6 V		6	10		15		13	

switching characteristics over recommended operating free-air temperature range, $C_L = 150$ pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC}	$T_A = 25^\circ\text{C}$			SN54HC623		SN74HC623		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{pd}	A or B	B or A	2 V		44	135		200		170	ns
			4.5 V		14	27		40		34	
			6 V		11	23		34		29	
t_{en}	\overline{OEBA}	A	2 V		130	270		405		335	ns
			4.5 V		31	54		81		67	
			6 V		23	46		69		56	
	OEAB	B	2 V		130	270		405		335	ns
			4.5 V		31	54		81		67	
			6 V		23	46		69		56	
t_t		A or B	2 V		45	210		315		265	ns
			4.5 V		17	42		63		53	
			6 V		13	36		53		45	

operating characteristics, $T_A = 25^\circ\text{C}$

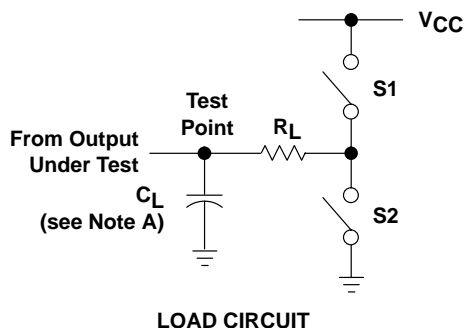
PARAMETER		TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance per transceiver	No load	40	pF

PRODUCT PREVIEW information concerns products in the formative or design phase of development. Characteristic data and other specifications are design goals. Texas Instruments reserves the right to change or discontinue these products without notice.

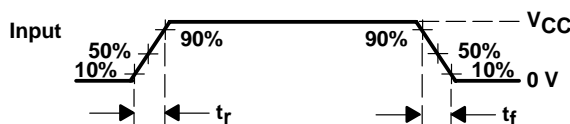


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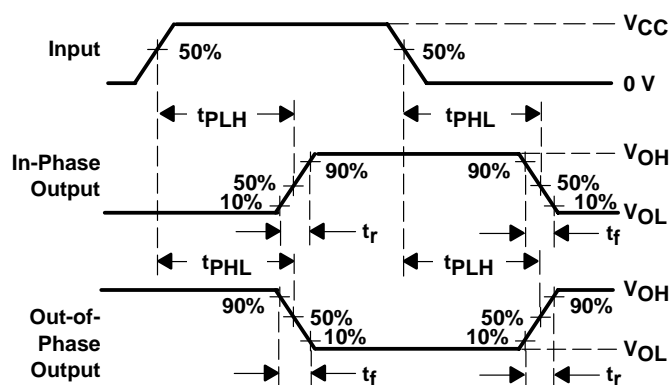
PARAMETER MEASUREMENT INFORMATION



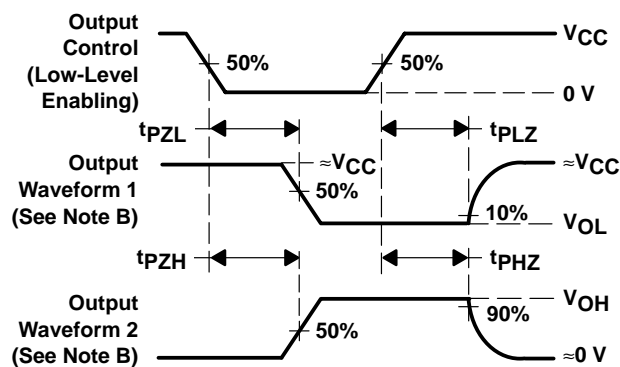
PARAMETER	R_L	C_L	$S1$	$S2$
t_{en}	1 k Ω	50 pF or 150 pF	Open	Closed
			Closed	Open
t_{dis}	1 k Ω	50 pF	Open	Closed
			Closed	Open
t_{pd} or t_t	—	50 pF or 150 pF	Open	Open



VOLTAGE WAVEFORM
INPUT RISE AND FALL TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY AND OUTPUT TRANSITION TIMES



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES FOR 3-STATE OUTPUTS

- NOTES:
- A. C_L includes probe and test-fixture capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: $PRR \leq 1$ MHz, $Z_O = 50 \Omega$, $t_r = 6$ ns, $t_f = 6$ ns.
 - D. The outputs are measured one at a time with one input transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74HC623DW	ACTIVE	SOIC	DW	20	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC623	Samples
SN74HC623N	ACTIVE	PDIP	N	20	20	RoHS & Non-Green	NIPDAU	N / A for Pkg Type	-40 to 85	SN74HC623N	Samples
SN74HC623NSR	ACTIVE	SO	NS	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC623	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74HC623NSR	SO	NS	20	2000	330.0	24.4	8.4	13.0	2.5	12.0	24.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74HC623NSR	SO	NS	20	2000	367.0	367.0	45.0

TUBE



*All dimensions are nominal

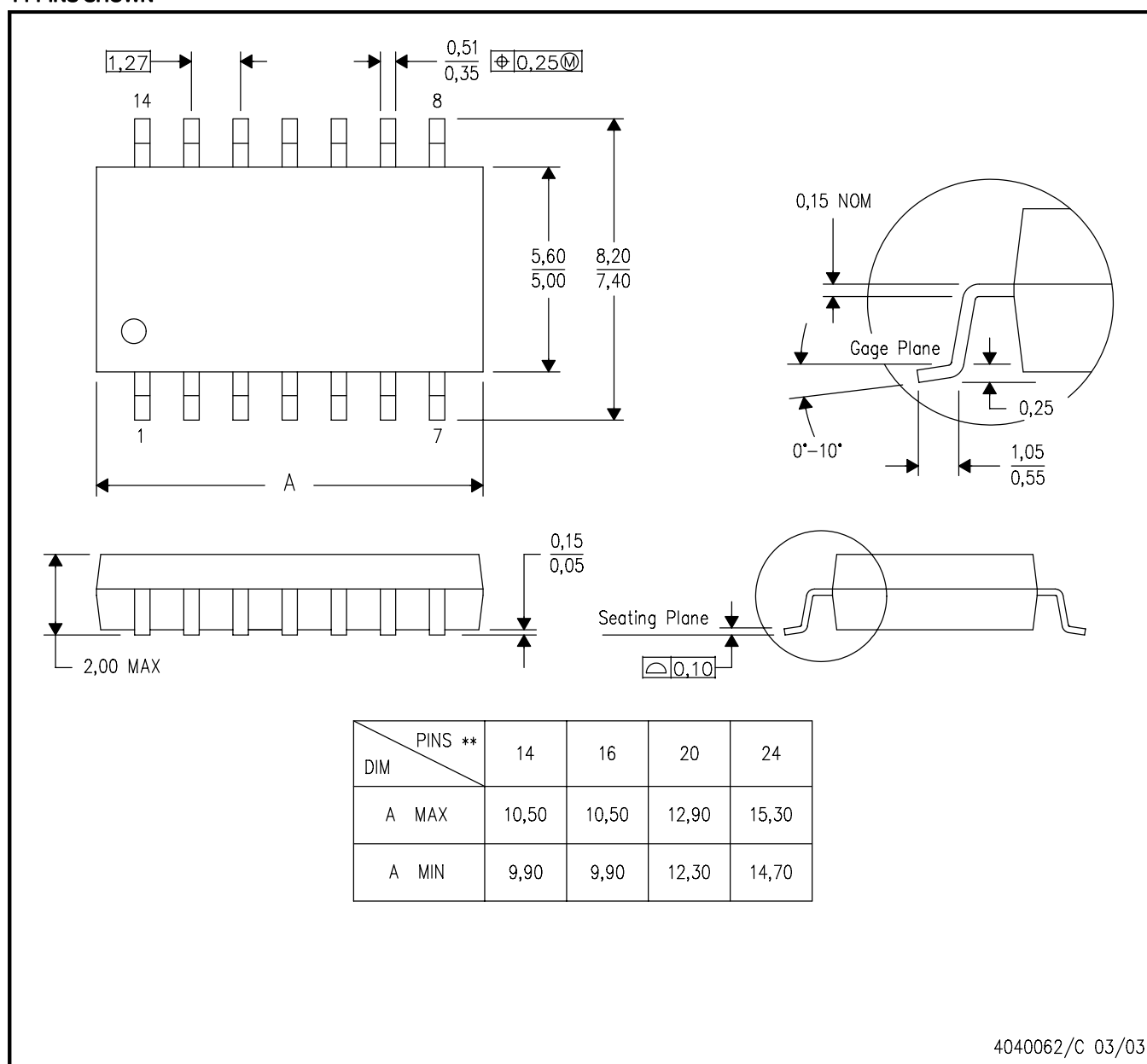
Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
SN74HC623DW	DW	SOIC	20	25	507	12.83	5080	6.6
SN74HC623N	N	PDIP	20	20	506	13.97	11230	4.32

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



PINS **	14	16	18	20
DIM				
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS-001 VARIATION	AA	BB	AC	AD



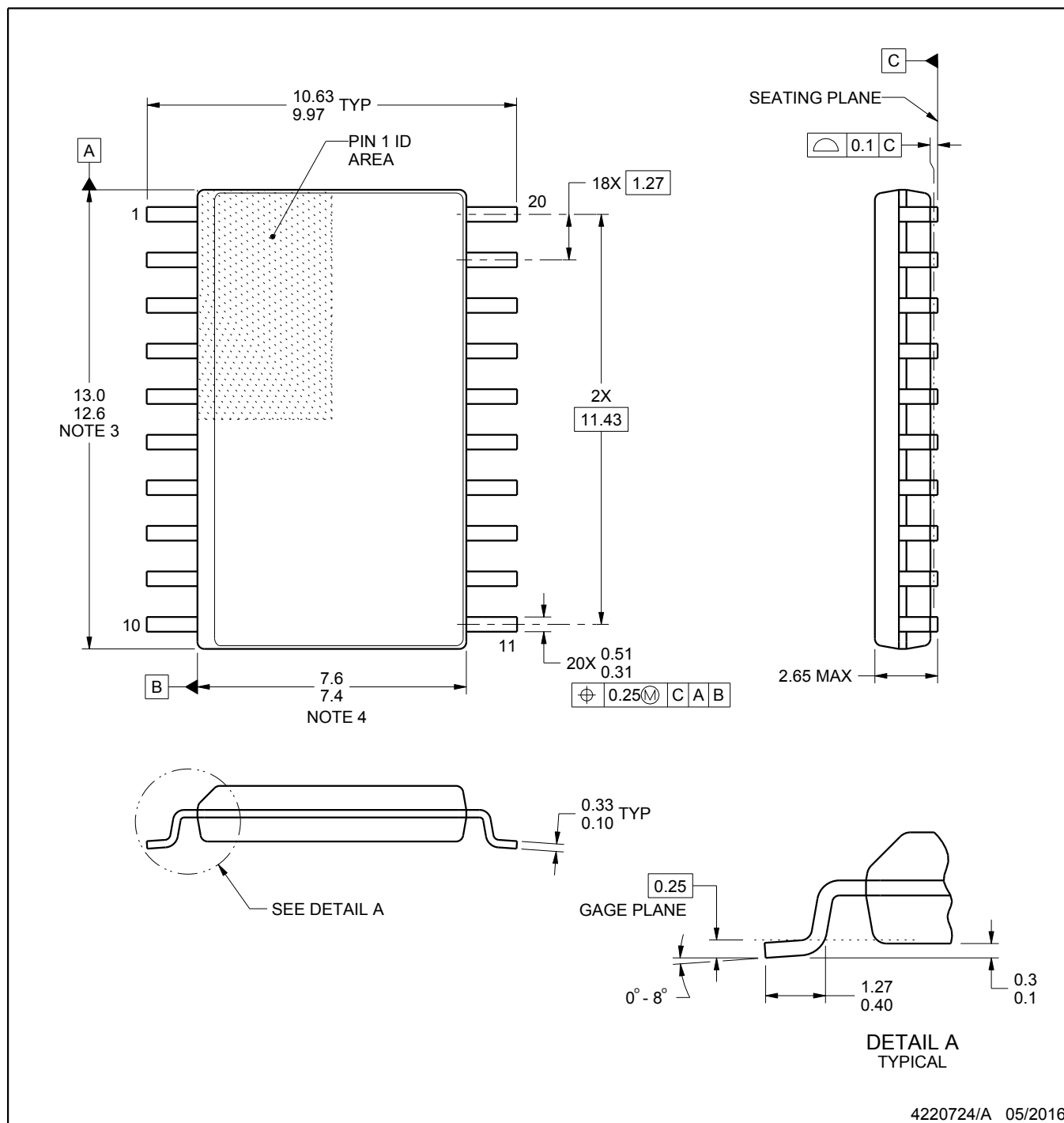
14/18 Pin Only
20 Pin vendor option

4040049/E 12/2002

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - The 20 pin end lead shoulder width is a vendor option, either half or full width.

DW0020A**PACKAGE OUTLINE****SOIC - 2.65 mm max height**

SOIC



4220724/A 05/2016

NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
5. Reference JEDEC registration MS-013.

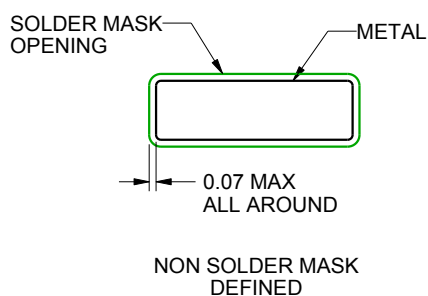
DW0020A

SOIC - 2.65 mm max height

SOIC



LAND PATTERN EXAMPLE
SCALE:6X



SOLDER MASK DETAILS

4220724/A 05/2016

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DW0020A

SOIC - 2.65 mm max height

SOIC



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:6X

4220724/A 05/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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